

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration
© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type\*
Distribute

**Declaration Class\*** Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information			
Company Name *	Company Unique ID	Unique ID Authority	Response Date*
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Aug 31, 2013 01:51 AM
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Ite	Mfr Item Number		Effe	ctive Date	Version	N	Manufacturing Site	Weight*	UOM	Unit Type	
2N7002KW	2N70	002KW	SOT-323 (G)				SUB	CONTRACTOR	0.005451	g	Each	
Manufacturing Process Information												
Terminal Finish	Base Alloy	J-STD-02	20 MSL Rating	Peak F	Peak Process Body Temperature		Max Time at Peak Temperature		No Ret	No Reflow cycles		
Matte Tin (Sn)	CU Alloy		1	260 C		С	30 se		30 seconds		3	

<sup>\*</sup> Required Field

## **RoHS Material Composition Declaration**

Declaration Type \* Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration \*

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance \* Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

None

**Declaration Signature** 

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Tand Loneasto

## **Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name SOT-323 (G)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.231	Supplier		Silicon	0.231	7440-21-3	42374
Encapsulation	Thermoplastics	3.684	Supplier		Carbon Black	0.037	1333-86-4	6759
			Supplier		Epoxy Resin	0.737	29690-82-2	135173
			Supplier		Silica, vitreous	2.911	60676-86-0	533932
Lead Frame	Other Ferrous alloys, non-stainless steels	1.294	Supplier		Iron	0.746	7439-89-6	136846
			В	Nickel (external applications only)	Nickel	0.518	7440-02-0	95021
			Supplier		Silver	0.030	7440-22-4	5503
Plating	Other Nonferrous metals & alloys	0.227	Supplier		Tin	0.227	7440-31-5	41641
Wire Bond	Precious metals	0.015	Supplier		Gold	0.015	7440-57-5	2752